

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2858471

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the ASSIGNEE NAME FROM TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD TO TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. previously recorded on Reel 032852 Frame 0313. Assignor(s) hereby confirms the THE CORRECTION OF ASSIGNEE NAME TO TAWIAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD..

CONVEYING PARTY DATA

Name	Execution Date
YI-JING LEE	03/19/2014
CHENG-HSIEN WU	03/17/2014
CHIH-HSIN KO	03/17/2014
CLEMENT HSINGJEN WANN	03/24/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14207848

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

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Email: ipdocketing@haynesboone.com
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Address Line 2: SUITE 700
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:	2013-1642 / 24061.2700
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/

PATENT

DATE SIGNED:	05/16/2014
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Total Attachments: 5

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>YI-JING LEE</td> <td>03/19/2014</td> </tr> <tr> <td>CHENG-HSIEN WU</td> <td>03/17/2014</td> </tr> <tr> <td>CHIH-HSIN KO</td> <td>03/17/2014</td> </tr> <tr> <td>CLEMENT HSINGJEN WANN</td> <td>03/24/2014</td> </tr> </tbody> </table>		Name	Execution Date	YI-JING LEE	03/19/2014	CHENG-HSIEN WU	03/17/2014	CHIH-HSIN KO	03/17/2014	CLEMENT HSINGJEN WANN	03/24/2014
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PATENT**REEL: 032918 FRAME: 0800**

CORRESPONDENCE DATA

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Address Line 2: SUITE 700
Address Line 4: DALLAS, TEXAS 75219

ATTORNEY DOCKET NUMBER:

2013-1642 / 24061.2700

NAME OF SUBMITTER:

DAVID M. O'DELL

Signature:

/David M. O'Dell/

Date:

05/08/2014

Total Attachments: 3

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RECEIPT INFORMATION

EPAS ID: PAT2847818
Receipt Date: 05/08/2014

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PATENT**REEL: 032918 FRAME: 0801**

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------------|----|---|
| (1) | Yi-Jing Lee | of | 2F., No. 87, Ln. 19, Guanxin Rd., East Dist.
Hsinchu City 300, Taiwan R.O.C. |
| (2) | Cheng-Hsien Wu | of | 7F.-2, No. 18, Ln. 107, Kexueyuan Rd., East Dist.
Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Chih-Hsin Ko | of | No. 1, Lane 200, Wunheng Rd., Kaohsiung County
Fongshan City 830, Taiwan, R.O.C. |
| (4) | Clement Hsingjen Wann | of | 1179 Barrett Circle West
Carmel, New York 10512, United States |

have invented certain improvements in

**IMPROVED FINFET DEVICES WITH UNIQUE FIN SHAPE AND THE
FABRICATION THEREOF**

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
_____ filed on _____ and assigned application number _____; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue

patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yi-Jing Lee

Residence Address: 2F., No. 87, Ln. 19, Guanxin Rd., East Dist.
Hsinchu City 300, Taiwan R.O.C.

✓ Dated: ^{2014.3.19}
Yi-Jing Lee

✓ Yi-Jing Lee
Inventor Signature

Inventor Name: Cheng-Hsien Wu

Residence Address: 7F.-2, No. 18, Ln. 107, Kexueyuan Rd., East Dist.
Hsinchu City 300, Taiwan, R.O.C.

✓ Dated: 2014.3.17

✓ Cheng-Hsien Wu
Inventor Signature

Inventor Name: Chih-Hsin Ko

Residence Address: No. 1, Lane 200, Wunheng Rd., Kaohsiung County
Fongshan City 830, Taiwan, R.O.C.

✓ Dated: ^{2014.3.17}
Chih-Hsin Ko

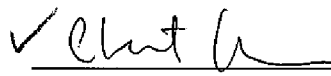
✓ Chih-Hsin Ko
Inventor Signature

Docket No.: 2013-1642/24061.2700
Customer No.: 000042717

Inventor Name: Clement Hsingjen Wann

Residence Address: 1179 Barrett Circle West Carmel, New York 10512, United States

Dated: 3/24/2014


Inventor Signature